



**SPECIFICATION
FOR
LCD Module
KD043FM-2B**

MODULE:	KD043FM-2B
CUSTOMER:	

REV	DESCRIPTION	DATE
1.0	FIRST ISSUE	2014.12.20

STARTEK	INITIAL	DATE
PREPARED BY		
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APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		



Revision History

[illegible]

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General Description

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 4.3'TFT-LCD contains 480x800 pixels, and can display up to 65K/262K/16.7M colors.

* Features

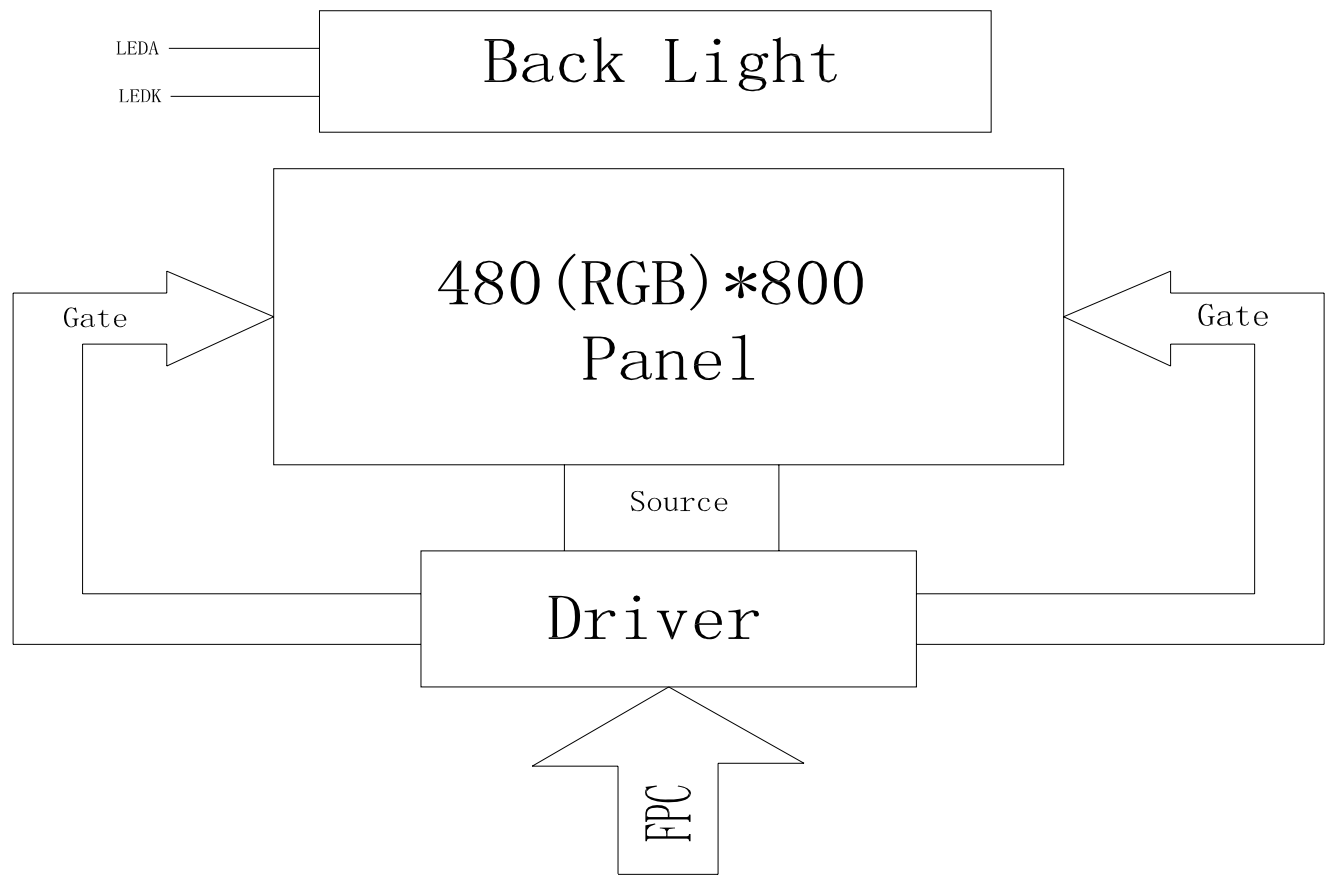
- Input Voltage: 3.3V(TYP)
- Display Colors of TFT LCD: 65K/262K/16.7M colors
- Interface:3SPI+16/18/24-bits RGB interface.

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	56.16(H)*93.6(V) (4.3inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K/16.7M	colors	-
Number of pixels	480(RGB)*800	dots	-
Pixel arrangement	RGB vertical stripe	-	-
Dot Pixel pitch	0.039*0.117mm(217ppi)	mm	-
Viewing angle	ALL	o'clock	-
Controller IC	ILI9806E	-	-
Display mode	Transmissive/Normally Black	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-

* Mechanical Information

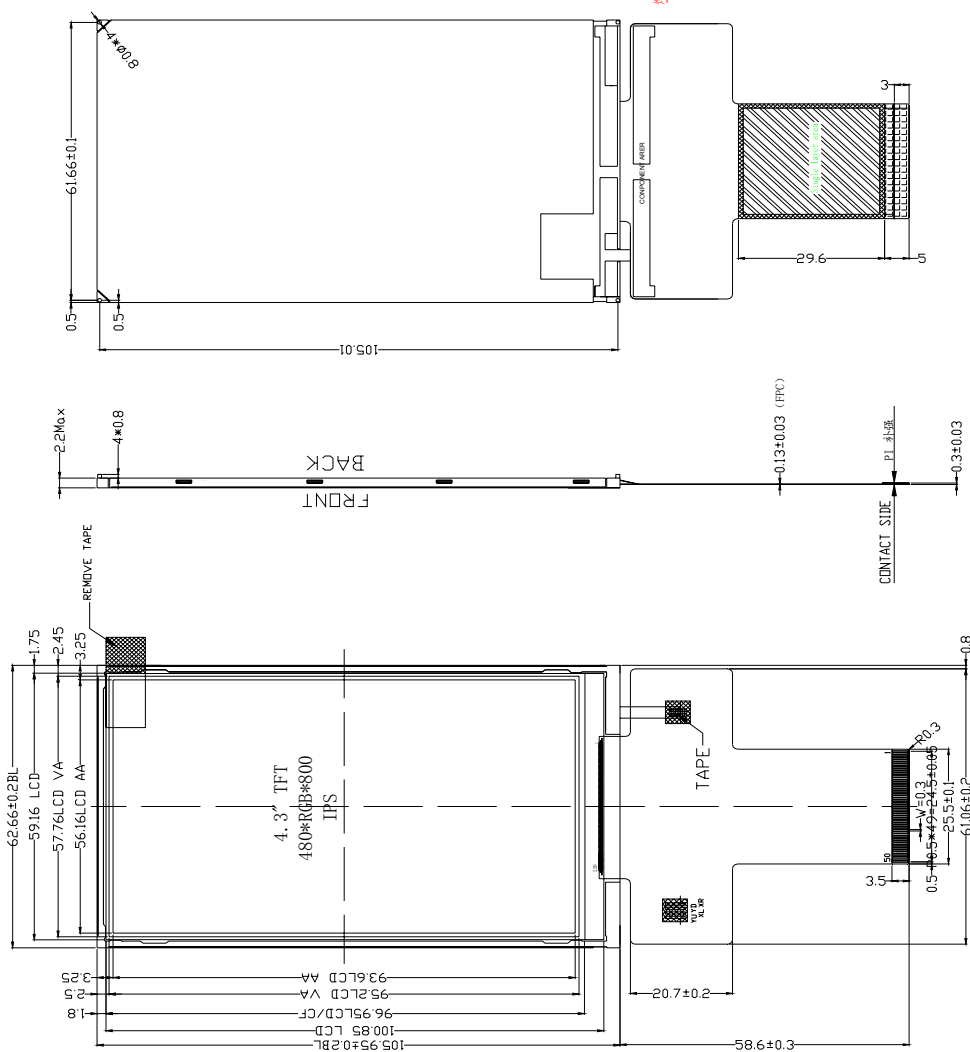
Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		62.66		mm	-
	Vertical(V)		105.95		mm	-
	Depth(D)		2.2		mm	-
Weight			TBD		g	-

1. Block Diagram





备注: 上机壳开窗需小于LCD/CF 0.3mm以上,
LCD V.A为建议镜片开窗区



FPC 弯折示意图

NOTE: Used RGB(DPI) interface

RGB Interface	DB Pin in use
16 Bit (565) RGB interface	DB0-D04, D08-D13, D16-D20
18 Bit (666) RGB interface	D00-D05, D08-D13, D16-D21
24 Bit (888) RGB interface	D00-D07, D08-D15, D16-D23

NOTE: If used RGB mode must select serial interface!

IND.	Pin Name																																																																																																		
1	LEDK	2	LEDA	3	NC	4	GND	5	GND	6	VCI	7	VCI	8	NC	9	NC	10	NC	11	NC	12	RESET	13	DB22(R7)	14	DB22(R8)	15	DB20(R4)	16	DB20(R4)	17	DB19(R3)	18	DB18(R2)	19	DB17(R1)	20	DB16(R7)	21	DB15(G3)	22	DB14(G6)	23	DB13(G2)	24	DB12(G4)	25	DB11(G3)	26	DB10(G2)	27	DB9(G1)	28	DB8(G0)	29	DB7(B7)	30	DB6(B6)	31	DB5(B5)	32	DB4(B4)	33	DB3(B3)	34	DB2(B2)	35	DB1(B1)	36	DB0(B0)	37	NC	38	NC	39	SQL	40	CS	41	SDI	42	SDO	43	VSYNC	44	HSYNC	45	DE	46	PCLK	47	XR	48	YD	49	XL	50	YU

Rev A	Revision content description	Date	TOLERANCES (公差) DIMENSIONS FIRST X.X ± 0.3 OTHERS SPECIFIED X.X ± 0.2			DRAWING NAME	KD043FM-2B Unit mm
					Checked		
						Approve	Page 1/1
							

LEDK ○ LEDA

LED (B/L) CIRCUIT

- NOTES:
1. DISPLAY TYPE: 4.3", TFT-LCD, 65K/262K/16.7M COLORS
 2. DISPLAY MODE: NORMALLY BLACK
 3. VIEWING DIRECTION: ALL
 4. DRIVER IC: IL1980GE (COG)
 5. VCI: 3.3V
 6. OPERATING TEMP: -20° C TO 70° C
STORAGE TEMP: -30° C TO 80° C
 7. BACK LIGHT: LED WHITE, 8 LED, 18-20mA, 2.5.6V ± 0.3V
 8. RoHS COMPLIANT.



3. Input terminal Pin Assignment

Pin NO.	Symbol	Function	I/O
1.	LEDK	Cathode pin of backlight.	P
2	LEDA	Anode pin of backlight.	P
3	NC	NC.	
4	GND	Ground.	P
5	GND	Ground.	P
6	VCI	Supply voltage (3.3V).	P
7	VCI	Supply voltage (3.3V).	P
8-11	NC	NC.	
12	RESET	Reset pin. Setting either pin low initializes the LSI. Must be reset after power is supplied.	I
13~36	DB23-DB16 (R7-R0) DB15-DB8 (G7-G0) DB7-DB0 (B7-B0)	Data bus PINS. 24-bit bi-directional data bus. 8-bit bus: use DB7-DB0 9-bit bus: use DB8-DB0 16-bit bus: use DB15-DB0 18-bit bus: use DB17-DB0 24-bit bus: use DB23-DB0 When Operation in MIPI DPI interface mode, it is an 18-bit bus RGB data bus. 24-bitbus: use DB23-DB0 16-bit bus: use DB15-DB0 18-bit bus: use DB17-DB0 If not used PINS, please must connect to GND.	I/O
37	NC		
38	NC		
39	SCL	Serial clock input.	I

40	CS	Chip select signal. Low: chip can be accessed; High: chip cannot be accessed.	I
41	SDI	Serial data input pin used for the SPI Interface. SDI : Serial data input pin SDA : Serial data input/output bidirectional pin.	I
42	SDO	Serial data output pin in serial bus system interface. If not used, please open this pin.	O
43	VSYNC	Serves VS signal pin on RGB interface. (Input pad). Must be connected to GND if not used.	I
44	HSYNC	Line synchronizing signal. Must be connected to GND or VCC if not used.	I
45	DE	A DATA ENABLE signal for DPI I/F mode. If not use, please connect to GND.	I
46	PCLK	Dot clock signal. Must be connected to GND if not used.	I
47	XR(NC)	NC.	A/D
48	YD(NC)	NC.	A/D
49	XL(NC)	NC.	A/D
50	YU(NC)	NC.	A/D

4. LCD Optical Characteristics

4.1 Optical specification

Optical characteristics are determined after the unit has been 'ON' and stable for approximately 30 minutes in a dark environment at 25 °C. The values specified are at an approximate distance 50 cm from the TFT-LCD surface at a viewing angle of Φ and θ equal to 0 °.

Measurement condition: Refer to next pages (LED back light with 20 mA/1 ea)

*1): with LGD Polarizer

*2): Only Color Filter glass base on C light spectrum

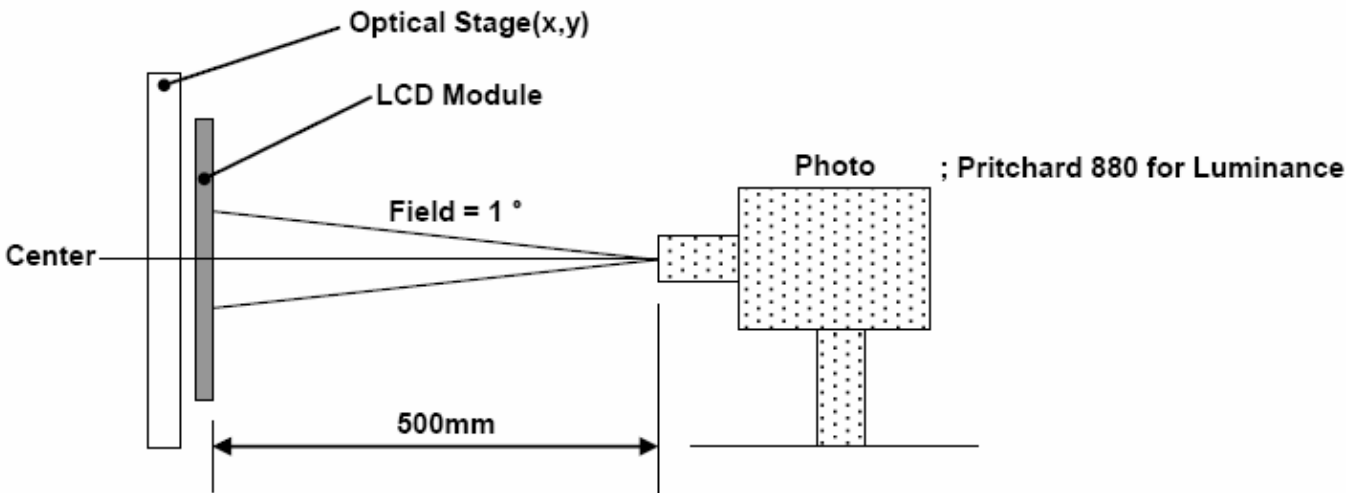
Parameter	Symbol	Values			Unit	Notes
		Min.	Typ.	Max.		
*1) Threshold Voltage	Vsat	3.4	3.6	3.8	V	Fig.2
	Vth	1.5	1.7	1.9	V	
*1) Transmittance	T(%)	4.1	4.5	-	%	Fig.1
*1) Contrast Ratio	C/R	-	800	-		
*1) Response Time	Tr	-	16	20	msec.	Fig.3
	Tf	-	14	20		
*2) CIE Color Coordinate	Ru'	0.444	0.459	0.474	-	
	Rv'	0.516	0.526	0.536	-	
	Gu'	0.111	0.120	0.129	-	
	Gv'	0.544	0.550	0.556	-	
	Bu'	0.121	0.136	0.151	-	
	Bv'	0.216	0.246	0.276	-	
	Wu'	-	0.192	-	-	
	Wv'	-	0.468	-	-	
*1) Viewing Angle	Θ_l	-	80	-	Degree	C/R>10 Fig.4
	Θ_r	-	80	-		
	Θ_u	-	80	-		
	Θ_d	-	80	-		

Note) Optical Specifications are depended on the Initial Code.

- Notes :
- Contrast Ratio(CR) is defined mathematically as :

$$\text{Contrast Ratio} = \frac{\text{Surface Luminance with all white pixels}}{\text{Surface Luminance with all black pixels}}$$
 - Surface luminance is the center point across the TFT-LCD surface 240 mm from the surface with all pixels displaying white. For more information see FIG 1.
 - Response time is the time required for the display to transition from black to white(Rise Time, Tr) and from white to black(Falling Time, Tf). For additional information see FIG 3.
 - Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the TFT-LCD surface. For more information see FIG 4.
 - Optimum contrast is obtained by adjusting the TFT-LCD Threshold voltage(Vth & Vsat)

[Test Equipment Set Up]



- Measuring Condition ;
 - Measuring surroundings : Dark Room
 - Measuring temperature : $T_a=25^{\circ}\text{C}$
 - Adjust operating voltage to get optimum contrast at the center of the display.
 - Measured value at the center point of LCD panel after more than 30 minutes while backlight turning on.

FIG. 2 The definition of Vth and Vsat

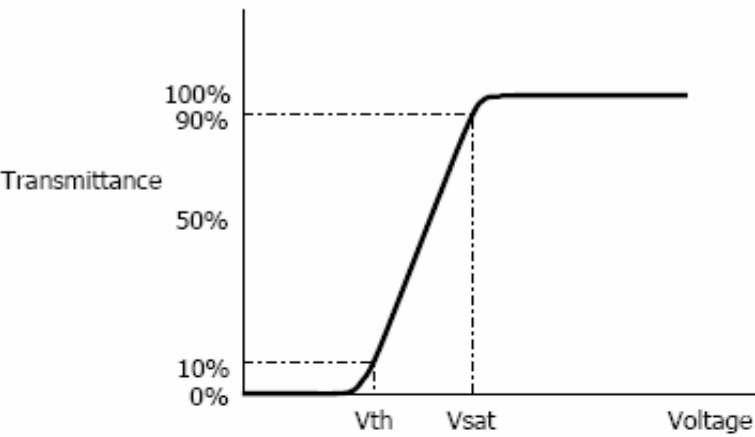
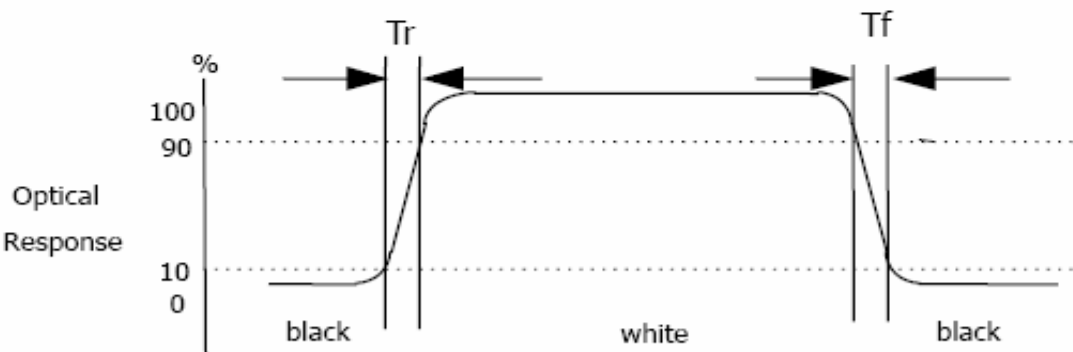


FIG. 3 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black"(0V) and "white"(5V).



* Voltage conditions for Response time at room temp. (25°C)
 Vgate : 20V DC
 Vdata : 0V~5V DC
 Vcom : 0V (Ground)

FIG. 4 The definition of viewing angle

<dimension of viewing angle range>

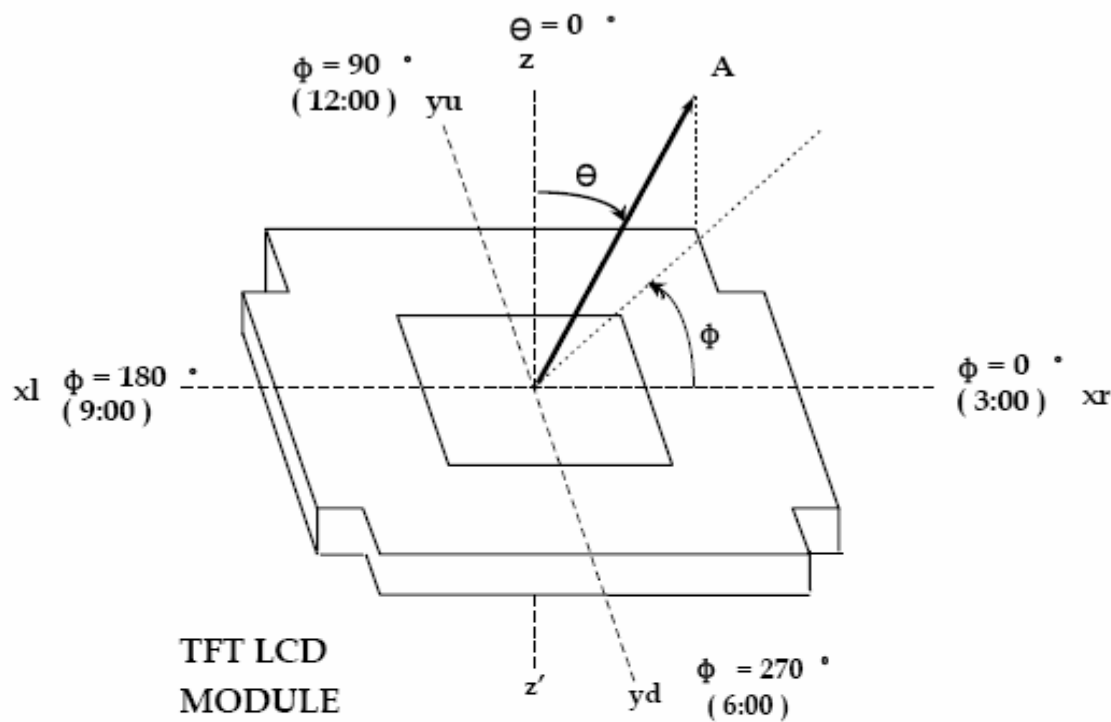
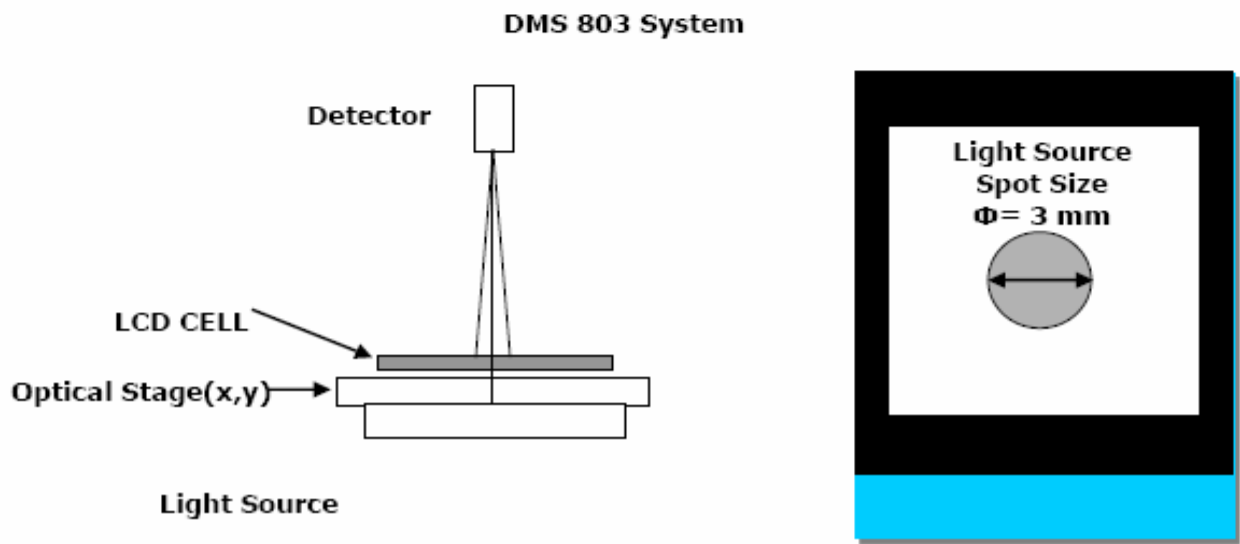


FIG. 5 Response Time Measurement Equipment and Method



5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital interface supply Voltage	VDDIO	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.5	3.3	3.6	V	--
Digital interface supply Voltage	VDDIO	1.65	3.3	3.6	V	--
Normal mode Current consumption	IDD	--	30	--	mA	--
Level input voltage	V _{IH}	0.7V _{DDIO}	--	V _{DDIO}	V	--
	V _{IL}	GND	--	0.3V _{DDIO}	V	--
Level output voltage	V _{OH}	V _{DDIO} -0.4	--	--	V	--
	V _{OL}	GND	--	GND+0.4	V	--

5.3 LED Backlight Characteristics

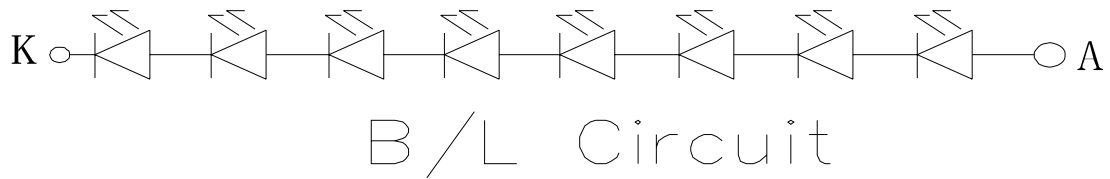
The back-light system is edge-lighting type with 8chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I _F	15	20	--	mA	--
Forward Voltage	V _F	--	25.6	--	V	--
LCM Luminance	L _V	400	--	--	cd/m ²	I _F =20mA
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	--



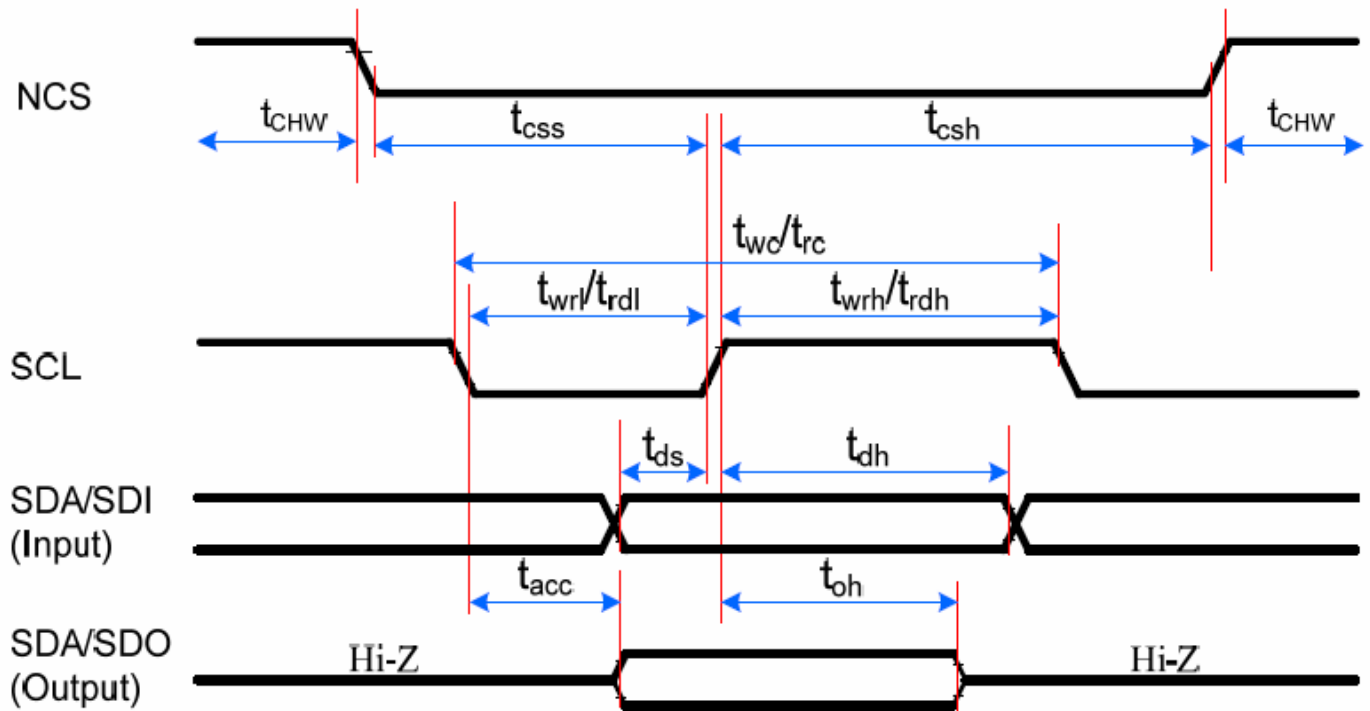
Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition:
 $T_a=25\pm3\text{ }^{\circ}\text{C}$, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at
 $T_a=25^{\circ}\text{C}$ and $I_L=40\text{mA}$. The LED lifetime could be decreased if operating I_L is larger than 40mA. The constant
current driving method is suggested.



6. AC Characteristic

6.1 Display Serial Interface Timing Characteristics (3-line SPI system)

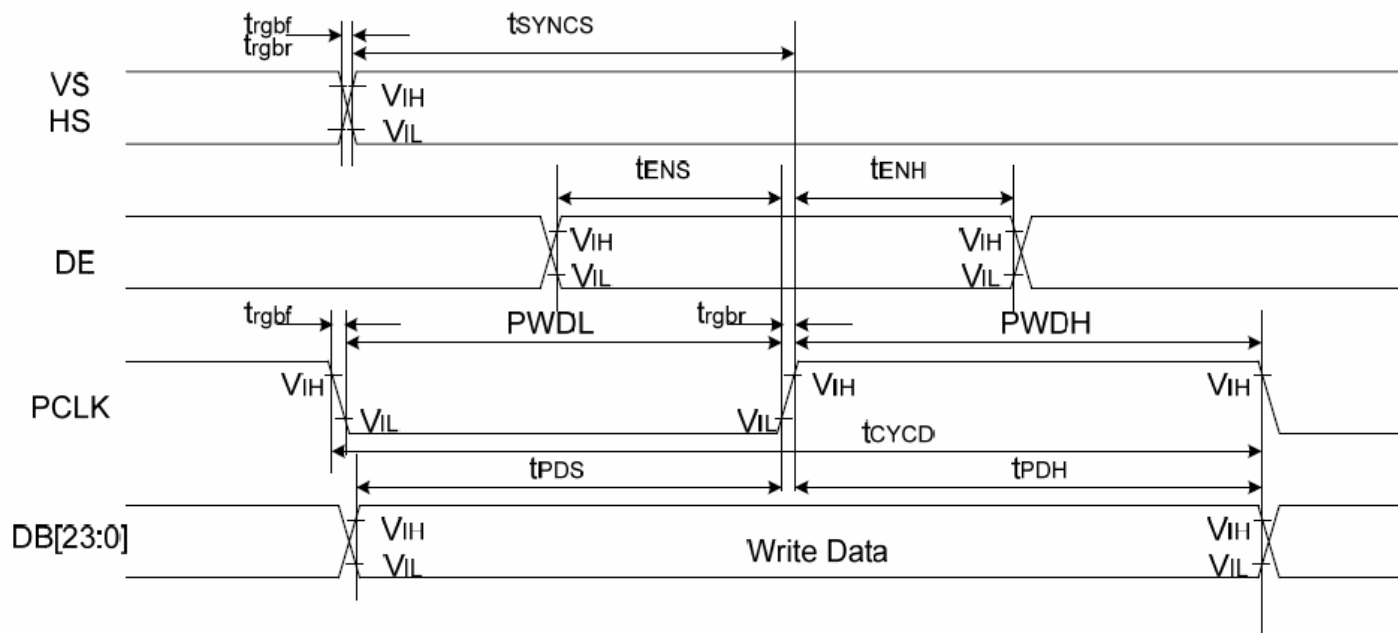


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	t _{css}	Chip select time (Write)	15	-	ns	
	t _{csh}	Chip select hold time (Read)	15	-	ns	
	t _{CHW}	CS "H" pulse width	40	-	ns	
SCL	t _{wc}	Serial clock cycle (Write)	30	-	ns	
	t _{wrh}	SCL "H" pulse width (Write)	10	-	ns	
	t _{wrl}	SCL "L" pulse width (Write)	10	-	ns	
	t _{rc}	Serial clock cycle (Read)	150	-	ns	
	t _{rdh}	SCL "H" pulse width (Read)	60	-	ns	
	t _{rdl}	SCL "L" pulse width (Read)	60	-	ns	
	t _{acc}	Access time (Read)	10	100	ns	For maximum CL=30pF
SDA/SDO (Output)	t _{oh}	Output disable time (Read)	15	100	ns	For minimum CL=8pF
	t _{ds}	Data setup time (Write)	10	-	ns	
SDA/SDI (Input)	t _{dh}	Data hold time (Write)	10	-	ns	

Note:

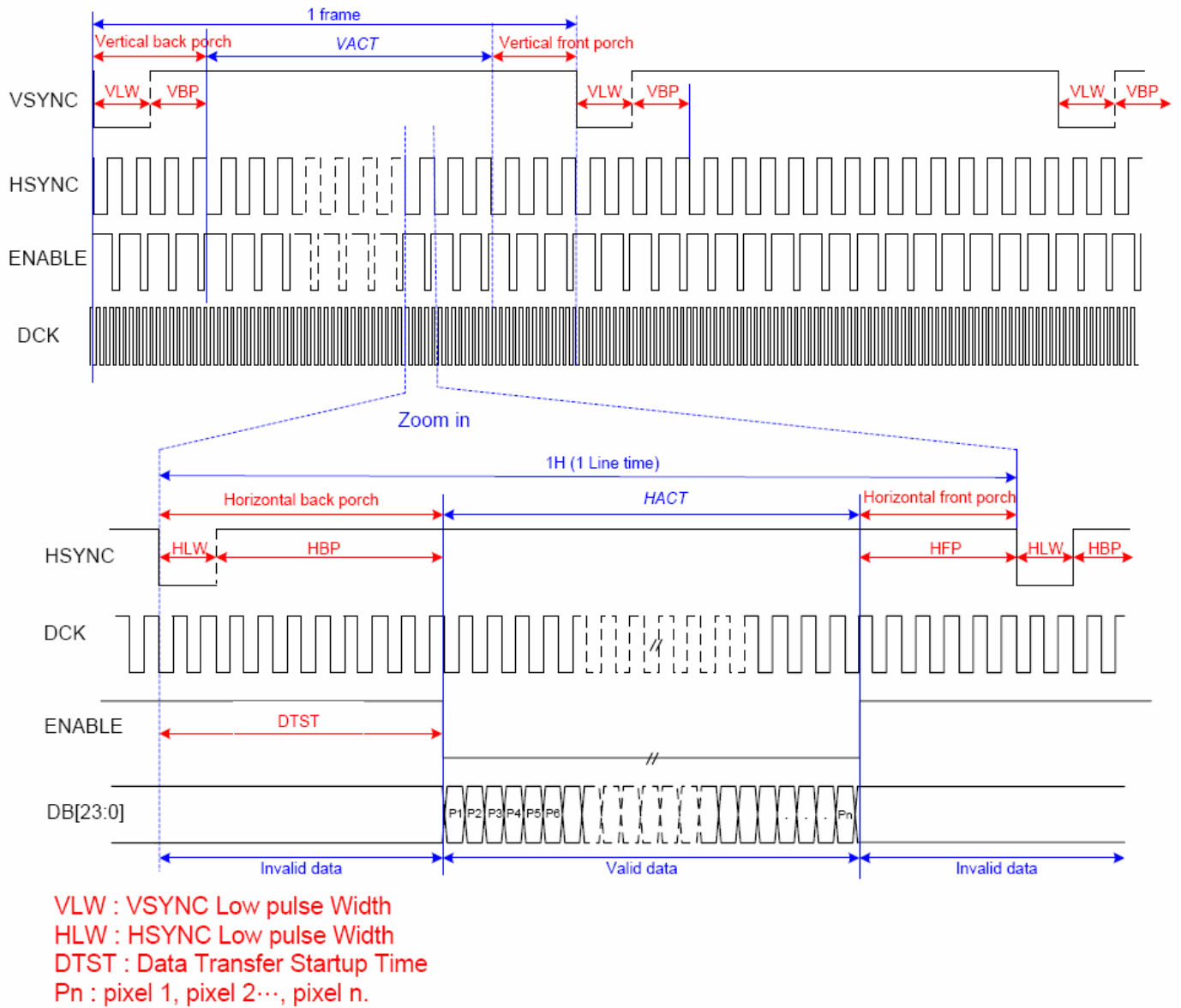
1. Ta = -30 to 70 °C, IOVCC=1.65V to 3.6V, VCI=2.5V to 3.6V, T=10+/-0.5ns.
2. Does not include signal rise and fall times.

6.2 Parallel 24/18/16-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VS/ HS	t_{SYNCS}	VS/HS setup time	5	-	ns	24/18/16-bit bus RGB interface mode
	t_{SYNCH}	VS/HS hold time	5	-	ns	
DE	t_{ENS}	DE setup time	5	-	ns	
	t_{ENH}	DE hold time	5	-	ns	
DB[23:0]	t_{POS}	Data setup time	5	-	ns	
	t_{PDH}	Data hold time	5	-	ns	
PCLK	$PWDH$	PCLK high-level period	13	-	ns	
	$PWDL$	PCLK low-level period	13	-	ns	
	t_{CYCD}	PCLK cycle time	28	-	ns	
	t_{rgbr}, t_{rgbf}	PCLK,HS,VS rise/fall time	-	15	ns	

Note: Ta = -30 to 70 °C, IOVCC=1.65V to 3.6V, VCI=2.5V to 3.6V, DGND=0V



Parameter	Symbols	Condition	Min.	Typ.	Max.	Units
Frame Rate	FR		54		66	fps
Horizontal Low Pulse width	HLW		1		-	DOTCLK
Horizontal Back Porch	HBP		2		126	DOTCLK
Horizontal Address	HACT			480		DOTCLK
Horizontal Front Porch	HFP		2		-	DOTCLK
Vertical Low Pulse width	VLW		1		126	Line
Vertical Back Porch	VBP		1		126	Line
Vertical Address	VACT				864	Line
Vertical Front Porch	VFP		1		255	Line
Data Clock	DCLK		16.6		41.7	MHz

6.5 Reset input timing

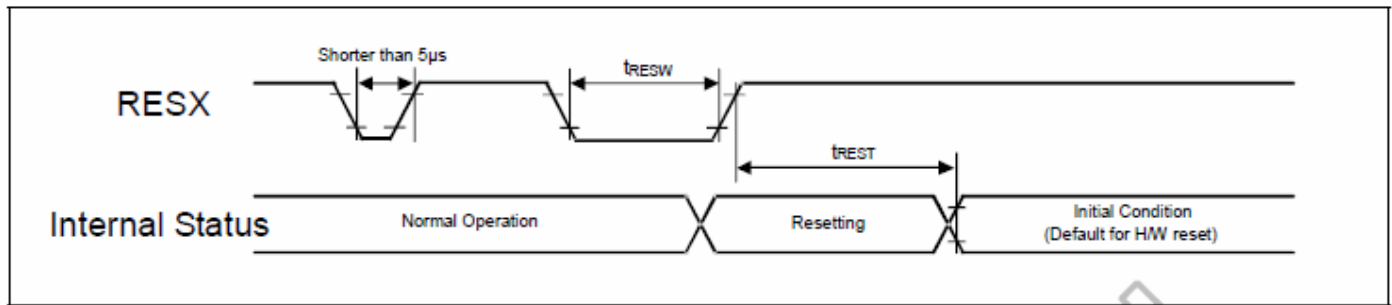


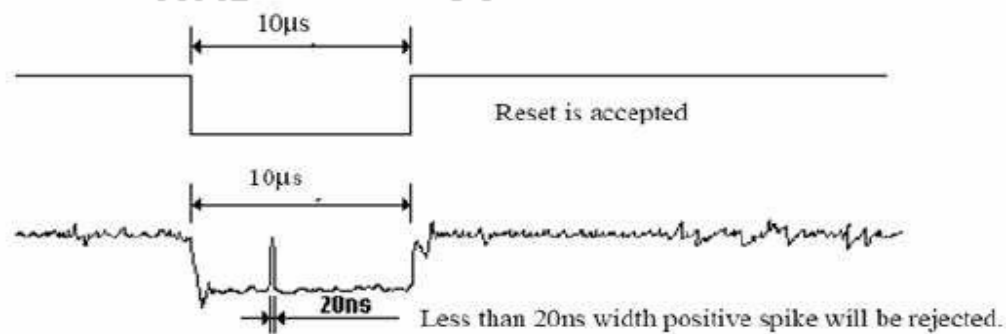
Figure 8.7: Reset input timing

Symbol	Parameter	Related pins	Min.	Typ.	Max.	Note	Unit
t_{RESW}	Reset low pulse width ⁽¹⁾	RESX	10	-	-	-	μs
t_{REST}	Reset complete time ⁽²⁾	-	-	-	5	When reset is applied during Sleep In mode	ms
		-	-	-	120	When reset is applied during Sleep Out mode	ms

Note: (1) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5 μ	Reset Rejected
Longer than 10 μs	Reset
Between 5 μs and 10 μs	Reset Start

- (2) During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then returns to Default condition for H/W reset.
- (3) During Reset Complete Time, ID2 value in OTP will be latched to internal register during this period. This loading is done every time when there is H/W reset complete time (t_{REST}) within 5ms after a rising edge of RESX.
- (4) Spike Rejection also applies during a valid reset pulse as shown below:



- (5) When Reset is applied during Sleep In Mode.
- (6) When Reset is applied during Sleep Out Mode.
- (7) It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

Table 8.10: Reset timing

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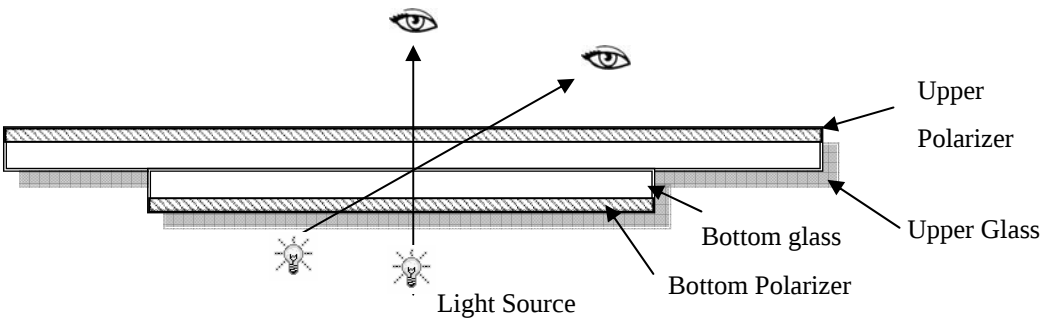
7. LCD Module Out-Going Quality Level

7.1 VISUAL & FUNCTION INSPECTION STANDARD

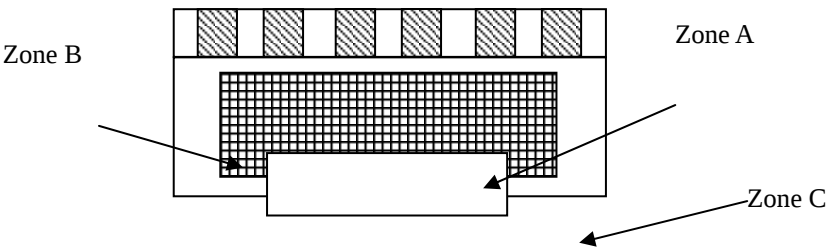
7.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

- Temperature : 25±5℃
- Humidity : 65%±10%RH
- Viewing Angle : Normal viewing Angle.
- Illumination: Single fluorescent lamp (300 to 700Lux)
- Viewing distance:30-50cm



7.1.2 Definition



- Zone A : Effective Viewing Area(Character or Digit can be seen)
- Zone B : Viewing Area except Zone A
- Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

7.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class II

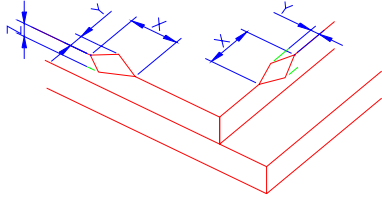
AQL:

Major defect	Minor defect
0.65	1.5

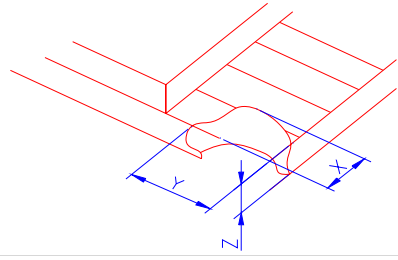
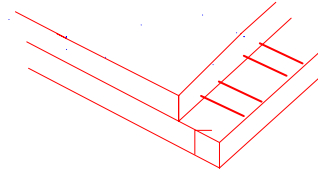
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Soldering appearance	Good soldering , Peeling off is not allowed.	
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

7.1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken	(1) The edge of LCD broken	 <table> <tr> <th>X</th><th>Y</th><th>Z</th></tr> <tr> <td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr> </table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
X	Y	Z						
≤3.0mm	<Inner border line of the seal	≤T						
NOTE: X: Length Y: Width Z: Height L: Length of ITO,								



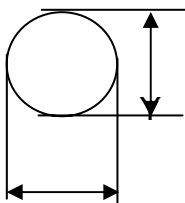
T: Height of LCD	(2)LCD corner broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	≤L	≤T
X	Y	Z						
≤3.0mm	≤L	≤T						
	(3) LCD crack	 Crack Not allowed						

Number	Items	Criteria (mm)
--------	-------	---------------



2.0

Spot defect



X

$$\Phi = (X+Y)/2$$

① light dot (LCD/TP/Polarizer black/white spot, light dot, pinhole, dent, stain)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.10$	Ignore		Ignore
$0.10 < \Phi \leq 0.15$	3(distance $\geq 10\text{mm}$)		
$0.15 < \Phi \leq 0.25$	1		
$0.25 < \Phi$	0		

② Dim spot (LCD/TP/Polarizer dim dot, light leakage, dark spot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.1$	Ignore		Ignore
$0.1 < \Phi \leq 0.2$	2(distance $\geq 10\text{mm}$)		
$0.2 < \Phi \leq 0.35$	1		
$\Phi > 0.35$	0		

③ Polarizer accidented spot

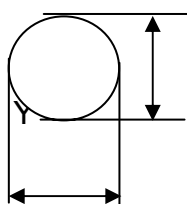
Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.2$	Ignore		Ignore
$0.2 < \Phi \leq 0.5$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.5$	0		

Line defect
(LCD/TP
/Polarizer
black/white
line, scratch,
stain)

Width(mm)	Length(mm)	Acceptable Qty		
		A	B	C
$\Phi \leq 0.03$	Ignore	Ignore		Ignore
$0.03 < W \leq 0.05$	L $\leq$ 3.0	N $\leq$ 2		
$0.05 < W \leq 0.08$	L $\leq$ 2.0	N $\leq$ 2		
$0.08 < W$	Define as spot defect			



Items	Criteria (mm)
Spot defect	<



X

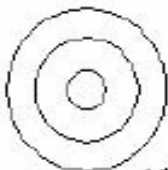
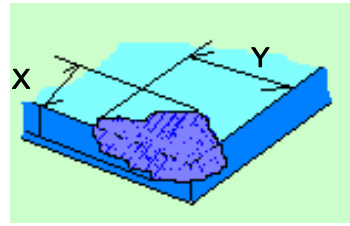
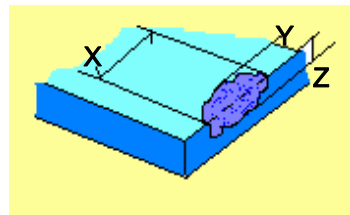
$$\Phi = (X + Y) / 2$$



Line defect (LCD/TP /Polarizer black/white line, scratch, stain)	<table><tr><td rowspan="2">Width(mm)</td><td rowspan="2">Length(mm)</td><td colspan="3">Acceptable Qty</td></tr><tr><td>A</td><td>B</td><td>C</td></tr><tr><td>$\Phi \leq 0.03$</td><td>Ignore</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr><tr><td>$0.03 < W \leq 0.05$</td><td>$L \leq 3.0$</td><td colspan="2">$N \leq 2$</td></tr><tr><td>$0.05 < W \leq 0.08$</td><td>$L \leq 2.0$</td><td colspan="2">$N \leq 2$</td></tr><tr><td>$0.08 < W$</td><td colspan="4">Define as spot defect</td></tr></table>					Width(mm)	Length(mm)	Acceptable Qty			A	B	C	$\Phi \leq 0.03$	Ignore	Ignore		Ignore	$0.03 < W \leq 0.05$	$L \leq 3.0$	$N \leq 2$		$0.05 < W \leq 0.08$	$L \leq 2.0$	$N \leq 2$		$0.08 < W$	Define as spot defect			
	Width(mm)	Length(mm)	Acceptable Qty																												
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	$0.08 < W$	Define as spot defect																													
Polarizer Bubble	<table><tr><td rowspan="2">Zone Size (mm)</td><td colspan="3">Acceptable Qty</td></tr><tr><td>A</td><td>B</td><td>C</td></tr><tr><td>$\Phi \leq 0.2$</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>$0.2 < \Phi \leq 0.4$</td><td colspan="2">2(distance $\geq 10\text{mm}$)</td></tr><tr><td>$0.4 < \Phi \leq 0.6$</td><td colspan="2">1</td></tr><tr><td>$0.6 < \Phi$</td><td colspan="2">0</td></tr></table>					Zone Size (mm)	Acceptable Qty			A	B	C	$\Phi \leq 0.2$	Ignore		Ignore	$0.2 < \Phi \leq 0.4$	2(distance $\geq 10\text{mm}$)		$0.4 < \Phi \leq 0.6$	1		$0.6 < \Phi$	0							
	Zone Size (mm)	Acceptable Qty																													
		A	B	C																											
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	$0.4 < \Phi \leq 0.6$	1																													
	$0.6 < \Phi$	0																													
SMT	According to IPC-A-610C class II standard . Function defect and missing part are major defect ,the others are minor defect.																														

		TP bubble/ accident spot	<table><tr><td rowspan="2">Size Φ(mm)</td><td colspan="3">Acceptable Qty</td></tr><tr><td>A</td><td>B</td><td>C</td></tr><tr><td>$\Phi \leq 0.1$</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>$0.1 < \Phi \leq 0.2$</td><td colspan="2">2 (distance $\geq 10\text{mm}$)</td></tr><tr><td>$0.2 < \Phi \leq 0.3$</td><td colspan="2">1</td></tr><tr><td>$0.3 < \Phi$</td><td colspan="2">0</td></tr></table>				Size Φ (mm)	Acceptable Qty			A	B	C	$\Phi \leq 0.1$	Ignore		Ignore	$0.1 < \Phi \leq 0.2$	2 (distance $\geq 10\text{mm}$)		$0.2 < \Phi \leq 0.3$	1		$0.3 < \Phi$	0		
Size Φ (mm)	Acceptable Qty																										
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$0.2 < \Phi \leq 0.3$	1																										
$0.3 < \Phi$	0																										
	Assembly deflection	beyond the edge of backlight $\leq 0.15\text{mm}$																									



5.0	TP Related			 1 规律性						
		Newton Ring	Newton Ring area>1/3 TP area Newton Ring area≤1/3 TP area	NG OK						
				 2 非规律性						
				 似牛顿环						
		TP corner broken X : length Y : width Z : height	<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>X≤3.0mm</td><td>Y≤3.0mm</td><td>Z<LCD thickness</td></tr></table> * Circuitry broken is not allowed.	X	Y	Z	X≤3.0mm	Y≤3.0mm	Z<LCD thickness	
X	Y	Z								
X≤3.0mm	Y≤3.0mm	Z<LCD thickness								
		TP edge broken X : length Y : width Z : height	<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>X≤6.0mm</td><td>Y≤2.0mm</td><td>Z<LCD thickness</td></tr></table> * Circuitry broken is not allowed.	X	Y	Z	X≤6.0mm	Y≤2.0mm	Z<LCD thickness	
X	Y	Z								
X≤6.0mm	Y≤2.0mm	Z<LCD thickness								



Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

8. Reliability Test Result

8.1 Condition

Item	Condition	Sample Size	Test Result	Note
Low Temperature Operating Life test	-20℃, 96HR	3ea	pass	-
Thermal Humidity Operating Life test	60℃, 90%RH, 96HR	3ea	pass	-
Temperature Cycle ON/OFF test	-20℃ ↔ 70℃, ON/OFF, 20CYC	3ea	pass	(1)
High Temperature Storage test	80℃, 96HR	3ea	pass	-
Low Temperature Storage test	- 30℃, 96HR	3ea	pass	-
Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	3ea	pass	
Box Drop Test	1 Corner 3 Edges 6 faces, 66cm(MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds

9. Cautions and Handling Precautions

9.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the "Power ON" condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

9.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%

(2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

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10.Packing

---TBD----